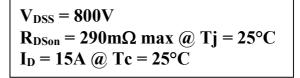
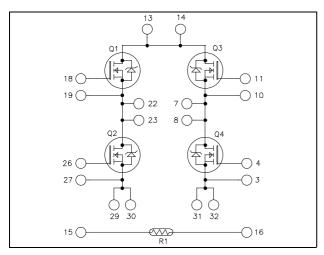


Full - Bridge Super Junction MOSFET Power Module





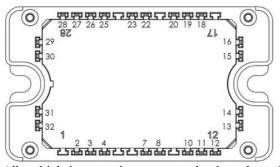
Application

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies

Features

• Super junction MOSFET

- Ultra low R_{DSon}
- Low Miller capacitance
- Ultra low gate charge
- Avalanche energy rated
- Very rugged
- Kelvin source for easy drive
- Very low stray inductance
- Internal thermistor for temperature monitoring



All multiple inputs and outputs must be shorted together Example: 13/14; 29/30; 22/23 ...

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Low profile
- Each leg can be easily paralleled to achieve a phase leg of twice the current capability
- RoHS Compliant

All ratings (a) $T_i = 25^{\circ}C$ unless otherwise specified

Absolute maximum ratings (per super junction MOSFET)

Symbol	Parameter	,	Max ratings	Unit
$V_{ m DSS}$	Drain - Source Voltage		800	V
T	Continuous Drain Current	$T_c = 25^{\circ}C$	15	
I_D	Continuous Drain Current	$T_c = 80^{\circ}C$	11	A
I_{DM}	Pulsed Drain current		60	
V_{GS}	Gate - Source Voltage		±30	V
R_{DSon}	Drain - Source ON Resistance		290	mΩ
P_D	Power Dissipation $T_c = 25^{\circ}C$		156	W
I_{AR}	Avalanche current (repetitive and non repetitive)		17	A
E_{AR}	Repetitive Avalanche Energy		0.5	Т
Eas	Single Pulse Avalanche Energy		670	mJ

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

Electrical Characteristics (per super junction MOSFET)

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0V, V_{DS} = 800V$			25	μΑ
R _{DS(on)}	Drain – Source on Resistance	$V_{GS} = 10V, I_D = 7.5A$			290	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 1 \text{mA}$	2.1	3	3.9	V
I_{GSS}	Gate – Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

Dynamic Characteristics (per super junction MOSFET)

Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit
C_{iss}	Input Capacitance	$V_{GS} = 0V$		2254		
C_{oss}	Output Capacitance	$V_{DS} = 25V$		1046		pF
C_{rss}	Reverse Transfer Capacitance	f = 1MHz		54		
$Q_{\rm g}$	Total gate Charge	$V_{GS} = 10V$		90		
Q_{gs}	Gate – Source Charge	$V_{Bus} = 400V$		11		nC
Q_{gd}	Gate – Drain Charge	$I_D = 15A$		45		
T _{d(on)}	Turn-on Delay Time	Inductive switching @125°C		10		
T_{r}	Rise Time	$V_{GS} = 15V$		13		
$T_{d(off)}$	Turn-off Delay Time	$V_{Bus} = 533V$ $I_D = 15A$		83		ns
T_{f}	Fall Time	$R_G = 5\Omega$		35		
Eon	Turn-on Switching Energy	Inductive switching @ 25°C		243		T
E_{off}	Turn-off Switching Energy	$V_{GS} = 15V, V_{Bus} = 533V$ $I_D = 15A, R_G = 5\Omega$		139		μJ
Eon	Turn-on Switching Energy	Inductive switching @ 125°C		425		т
E _{off}	Turn-off Switching Energy	$V_{GS} = 15V, V_{Bus} = 533V$ $I_D = 15A, R_G = 5\Omega$		171		μJ
R _{thJC}	Junction to Case Thermal Resistance	e			0.80	°C/W

Source - Drain diode ratings and characteristics (per super junction MOSFET)

Source Prairie arous rusings and characteristics (per super junction in earlier)							
Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
т	Continuous Source current		$Tc = 25^{\circ}C$		15		۸
I_{S}	(Body diode)		$Tc = 80^{\circ}C$		11		Α
V_{SD}	Diode Forward Voltage	$V_{GS} = 0V, I_S = -15A$	<u>.</u>			1.2	V
dv/dt	Peak Diode Recovery •					6	V/ns
t_{rr}	Reverse Recovery Time	$I_S = -15A$; $V_R = 400$)V		550		ns
Q_{rr}	Reverse Recovery Charge	$di_S/dt = 100A/\mu s$			15		μC

• dv/dt numbers reflect the limitations of the circuit rather than the device itself.

 $I_S \leq \text{--} 15 A \qquad di/dt \leq 100 A/\mu s \qquad V_R \leq V_{DSS} \qquad T_j \leq 150 ^{\circ} C$



Thermal and package characteristics

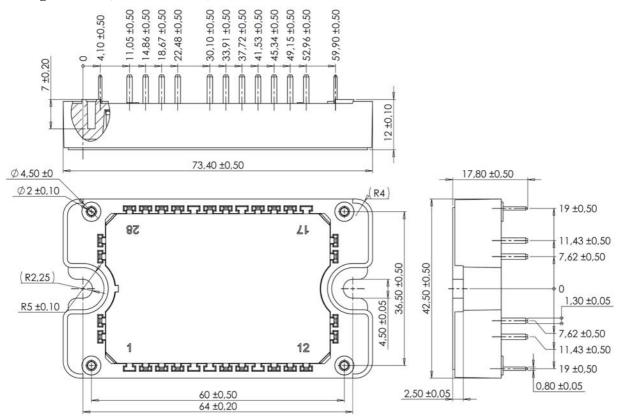
Symbol	Characteristic			Min	Max	Unit	
V_{ISOL}	RMS Isolation Voltage, any terminal to case t = 1 min, 50/60Hz			4000		V	
$T_{\rm J}$	Operating junction temperature range			-40	150		
T_{JOP}	Recommended junction temperature under switching conditions			-40	T _J max -25	°C	
T_{STG}	Storage Temperature Range			-40	125	C	
$T_{\rm C}$	Operating Case Temperature			-40	125		
Torque	Mounting torque	To heatsink	M4	2	3	N.m	
Wt	Package Weight			110	g		

Temperature sensor NTC (see application note APT0406 on www.microsemi.com for more information).

Symbol	Characteristic		Min	Typ	Max	Unit
R ₂₅	Resistance @ 25°C	C		50		kΩ
$\Delta R_{25}/R_{25}$				5		%
B _{25/85}	$T_{25} = 298.15 \text{ K}$			3952		K
$\Delta \mathrm{B/B}$		T _C =100°C		4		%

$$R_{T} = \frac{R_{25}}{\exp\!\left[B_{25/85}\!\left(\frac{1}{T_{25}}\!-\!\frac{1}{T}\right)\right]} \quad \text{T: Thermistor temperature} \\ R_{T} : \text{Thermistor value at T}$$

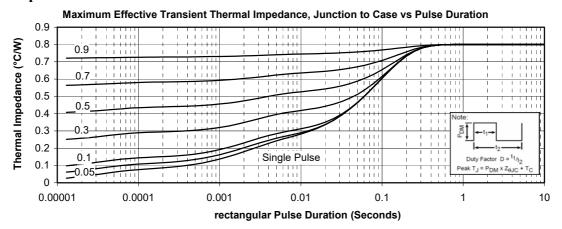
Package outline (dimensions in mm)

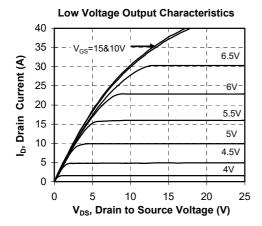


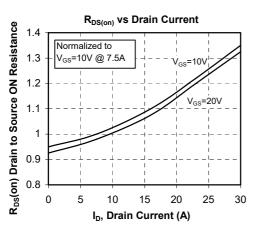
 $See \ application \ note \ 1906 - Mounting \ Instructions \ for \ SP3F \ Power \ Modules \ on \ www.microsemi.com$

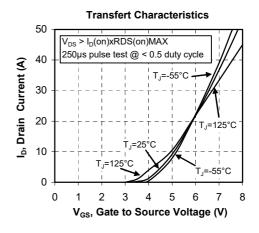


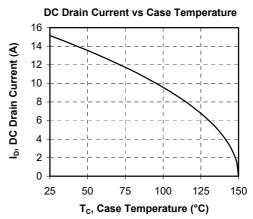
Typical performance Curve



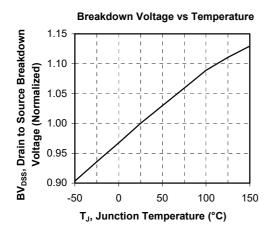


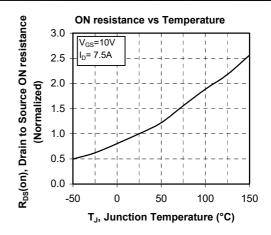


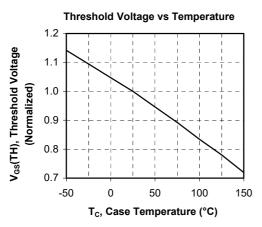


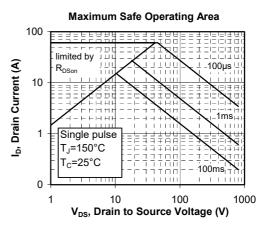


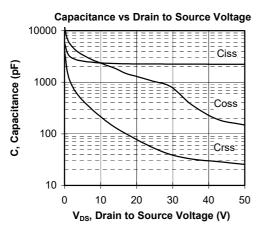


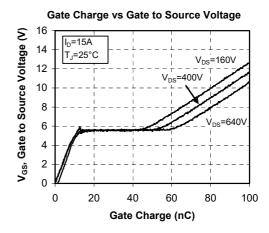




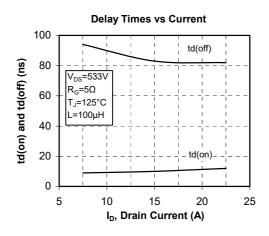


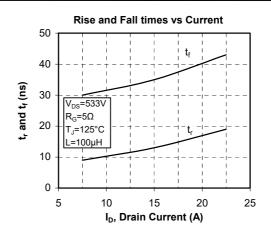


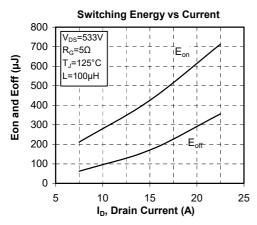


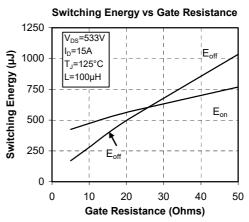


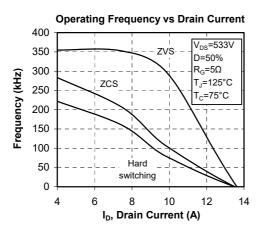


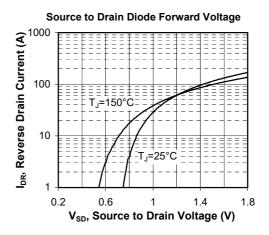












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